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High-k Materials and Devices 2014

Guest Editor:

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submissions:

closed (15 January 2014)

Message from the Guest Editor

Dear Colleagues,

Advanced gate stacks with high dielectric constant materials (high-k) for complementary metal-oxide-semiconductor (CMOS) and memory applications in sub-22 nm feature size integrated circuits have been a subject of intense research in recent years. The main focus of the forthcoming special issue is to present a comprehensive overview to our readers by assembling state-of-the-art research articles and reviews on processing and characterization of high-k gate material. The topics covered by this special issue include high-k materials and deposition methods; Deposition on high-mobility substrate such as Ge, GaAs, and other III-V compounds; Interface passivation of substrate/high-k interface; Reliability of high-k material; Characterization techniques and Application to non-volatile memory systems.

Prof. Dr. Durga Misra
Guest Editor



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Special Issue



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Message from the Editor-in-Chief

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